(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
26 June 2008 (26.06.2008)

PCT

(10) International Publication Number
WO 2008/075970 A1

(51) International Patent Classification:
H01L 21/677 (2006.01) *B65G 49/06* (2006.01)
H01L 21/683 (2006.01) *B28D 5/00* (2006.01)

(21) International Application Number:
PCT/NO2007/000453

(22) International Filing Date:
19 December 2007 (19.12.2007)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/875,541 19 December 2006 (19.12.2006) US

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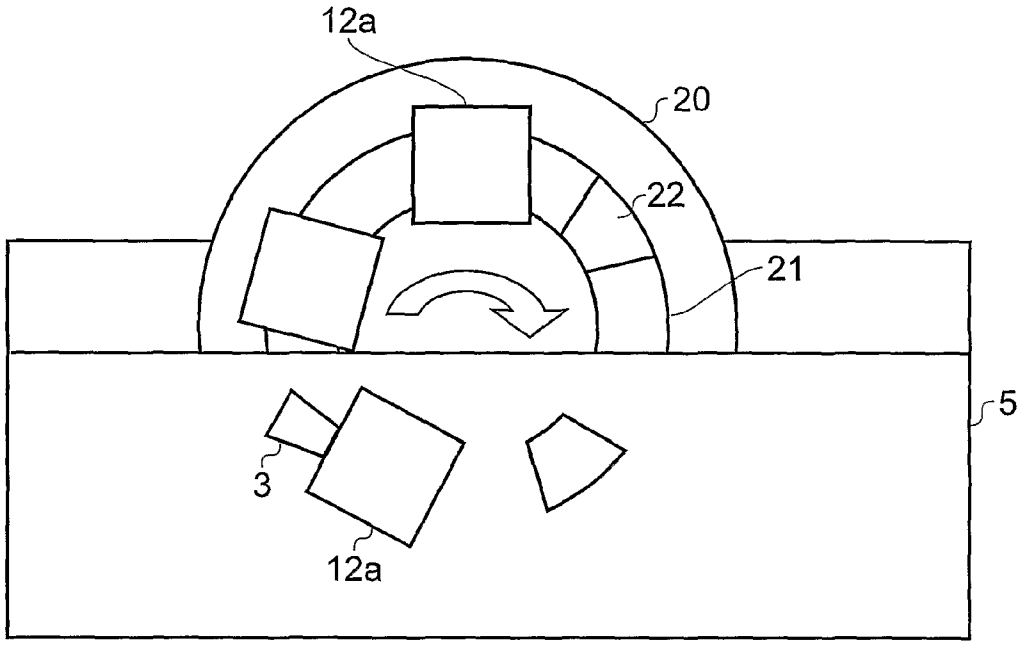
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(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, MT, NL, PL,

[Continued on next page]

(54) Title: METHOD AND DEVICE FOR SE ARATION OF SILICON WAFERS



(57) Abstract: The invention relates to a method for separation of a silicon wafer (12a) from a vertical stack (10) of silicon wafers (12). The method is characterised in that it comprises attaching a movable transport device (2) to a surface of the silicon wafer (12a) in the stack (10), and horizontal movement of the silicon wafer (12a) parallel (A) to the surface of the silicon wafer (12a) until the silicon wafer (12a) is separated from the stack (10). The invention also comprises a device for implementing the method.

WO 2008/075970 A1

PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— *with international search report*

— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*